

DEMI 400™ Series

SUPPORT & RESIN REMOVAL



The PostProcess™ DEMI 400™ Series leverages our proprietary patented Submersed Vortex Cavitation technology for revolutionary post-printing efficiencies; combining software, hardware, and chemistry features for optimal resin and support removal.

- AUTOMAT3D® intelligent software control of energy sources and simplified machine operation.
- Vortex pumping scheme ensures uniform chemistry exposure to finished parts with unprecedented consistency.
- Precision control over temperature and ultrasonic-generated cavitations for accelerated process times

SOFTWARE FEATURES	• Variable temperature: 86-145°F / 30-63°C • HMI enabled programmable cycle time • Proprietary Agitation Algorithms
HARDWARE FEATURES	• Stainless steel envelope • Magnetically driven pump • Casters for easy installation
MATERIALS AND TECHNOLOGIES	• Resin Removal: SLA, DLP, CLIP • Support Removal: FDM, POLYJET, WAX
SIZE	• Envelope: 14" L x 14" W x 14" H 35.5 cm x 35.5 cm x 35.5 cm • Footprint: 38.5" L x 27" W x 47" H 97.7 cm x 68.5 cm x 119.3 cm • Weight: 300 lbs empty / 136 kg 470 lbs full / 213 kg
CONSUMABLES	• Capacity: 17 Gallons (64 Liters) • Detergent: PLM-101-SUB for PolyJet PLM-201-SUB for FDM PLM-403-SUB for SLA, CLIP, DLP PLM-601-SUB for Wax
SAFETY FEATURES	• Emergency stop • Auto power down •  
ELECTRICAL - NORTH AMERICA	• DEMI 400 MODEL: Power: 120V, 60Hz, Connector: NEMA 5-15P • DEMI 430 MODEL: Power: 120V, 60Hz, Connector: NEMA 5-15P Dual agitation; includes heater & ultrasonic
ELECTRICAL - EUROPE	• DEMI 430 MODEL Power: 230V, 50Hz, Connector: CEE 7/3 Dual agitation; includes heater & ultrasonics